Micro Array Hole Formation in Glass Using Electrochemical Discharge Machining

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With the widespread application of non-conducting tough materials, such as glass in MEMS recent years, many difficulties have arisen in the processing of these kind of material with eigen-structure characteristics. In this paper, based on the technical advantages of electrochemical discharge machining, the mechanism of tool electrode structure and process parameters for the stability of gas film, processing efficiency and forming quality is analysed, and the machining of a glass micro-array hole is accomplished by obtaining the optimal process parameters.

Keywords: ECDM; micro array holes; gas film.

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